



Etek
Microelectronics

ES15DFCX

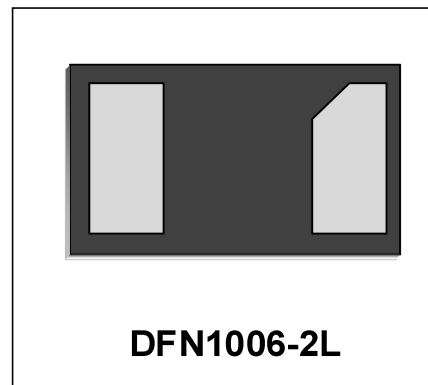
Transient Voltage Suppressor

Features

- 756 Watts Peak Pulse Power per Line ($t_p=8/20\mu s$)
- Small Body Outline Dimensions
- Protects one I/O or power line
- Working Voltage: 15V
- Low Leakage Current

IEC COMPATIBILITY (EN61000-4)

- IEC 61000-4-2 (ESD) $\pm 30kV$ (air), $\pm 30kV$ (contact)
- IEC 61000-4-4 (EFT) 40A (5/50ns)
- IEC 61000-4-5 (Lightning) 28A (8/20 μs)



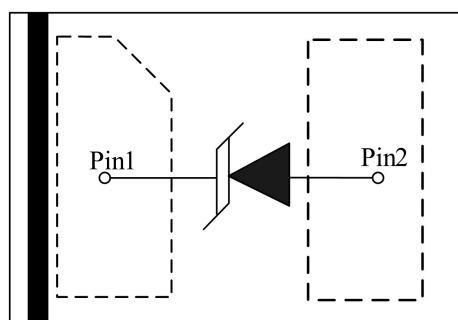
Mechanical Characteristics

- DFN1006-2L package
- Marking : Marking Code
- Packaging : Tape and Reel per EIA 481
- RoHS Compliant
- MSL1

Applications

- Cellular Handsets & Accessories
- Personal Digital Assistants (PDAs)
- Notebooks & Handhelds
- Portable Instrumentation
- Digital Cameras

Schematic & PIN Configuration



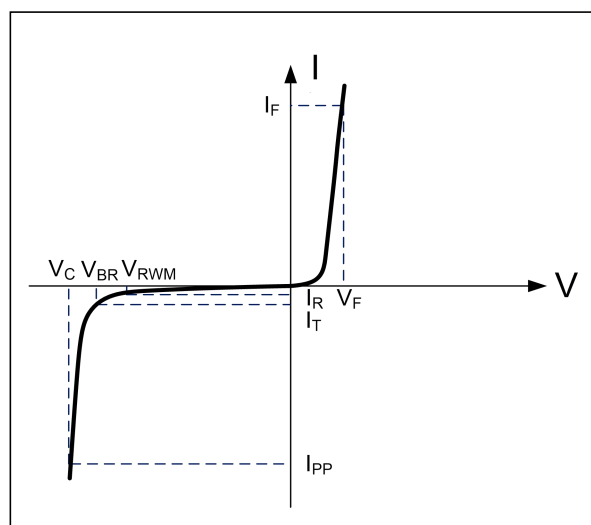
(TOP VIEW)

Absolute Maximum Rating

Rating	Symbol	Value	Units
Peak Pulse Power ($t_p = 8/20\mu s$)	P_{PP}	756	Watts
Peak Pulse Current ($t_p = 8/20\mu s$)	I_{PP}	28	A
Operating Temperature	T_J	-55 to + 125	°C
Storage Temperature	T_{STG}	-55 to +150	°C

Electrical Parameters (T=25°C)

Symbol	Parameter
I_{PP}	Reverse Peak Pulse Current
V_C	Clamping Voltage @ I_{PP}
V_{RWM}	Reverse Stand-Off Voltage
I_R	Reverse Leakage Current @ V_{RWM}
V_{BR}	Breakdown Voltage @ I_T
I_T	Test Current
I_F	Forward Current
V_F	Forward Voltage @ I_F



Electrical Characteristics

ES15DFCX						
Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Units
Reverse Stand-Off Voltage	V_{RWM}				15	V
Reverse Breakdown Voltage	V_{BR}	$I_T=1mA$	16		20	V
Reverse Leakage Current	I_R	$V_{RWM}=15V, T=25^\circ C$			500	nA
Forward Voltage	V_F	$I_F=10mA$	0.5		1.2	V
Clamping Voltage	V_C	$I_{PP}=28A, t_p=8/20\mu s$		24.5	27	V
Dynamic Resistance ^{1,2}	R_{DYN}	$TLP=0.2/100ns$		0.1		Ω
ESD Clamping Voltage ¹	V_C	$I_{PP} = 4A, t_p = 0.2/100ns (TLP)$		16.9		V
ESD Clamping Voltage ¹	V_C	$I_{PP} = 16A, t_p = 0.2/100ns (TLP)$		18.1		V
Junction Capacitance	C_j	$V_R = 0V, f = 1MHz$		180	220	pF

Note: 1、TLP Setting : $t_p=100ns, t_r=0.2ns, I_{TLP}$ and V_{TLP} sample window: $t_1=70ns$ to $t_2=90ns$.

2、Dynamic resistance calculated from $I_{PP}=4A$ to $I_{PP}=16A$ using "Best Fit"

Typical Characteristics

Figure 1: Peak Pulse Power vs. Pulse Time

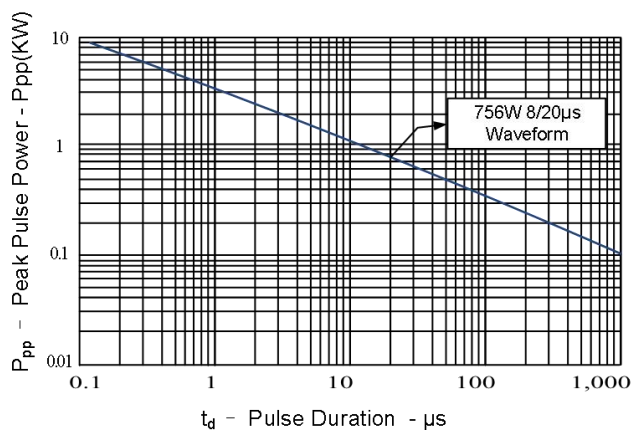


Figure 2: Power Derating Curve

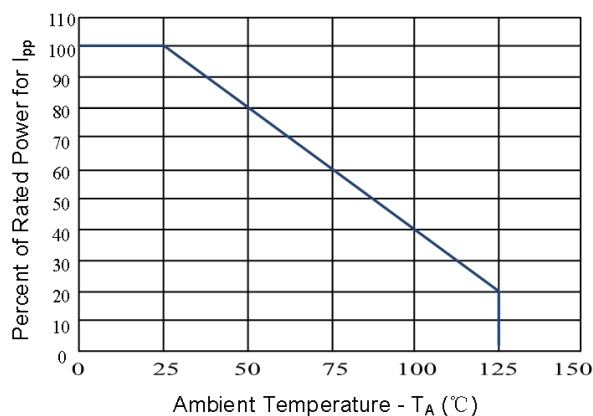


Figure 3: Clamping Voltage vs. Peak Pulse Current

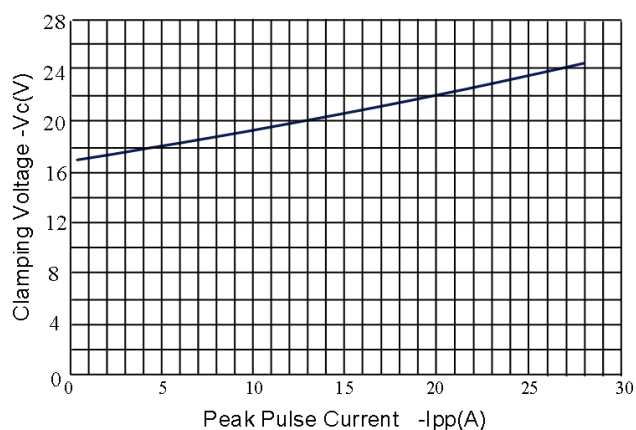


Figure 4: Normalized Junction Capacitance vs. Reverse Voltage

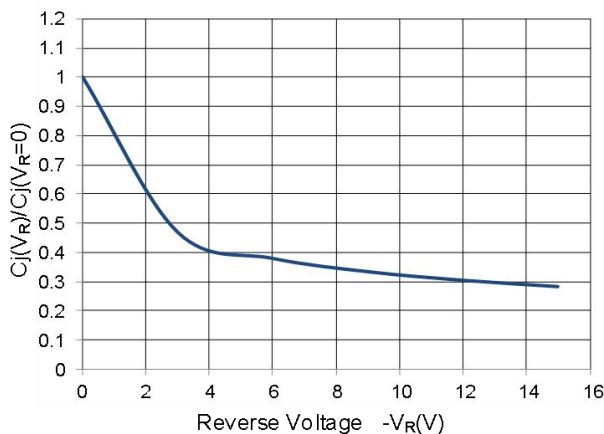


Figure 5: 8/20 μs Pulse Waveform

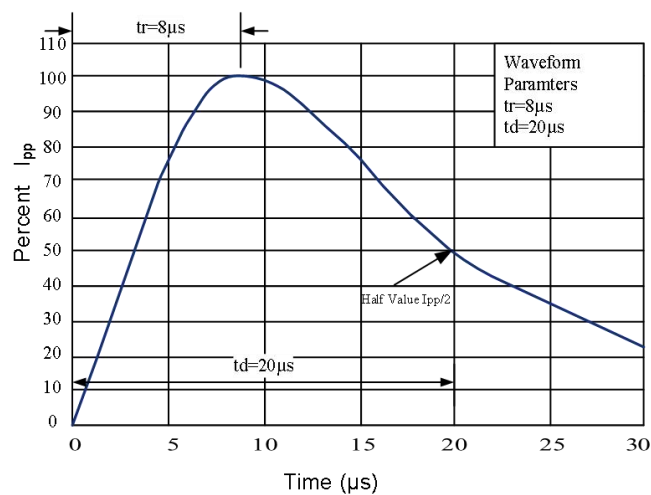
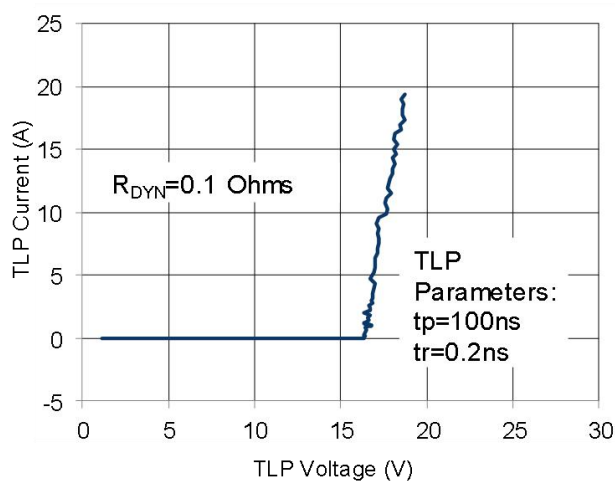
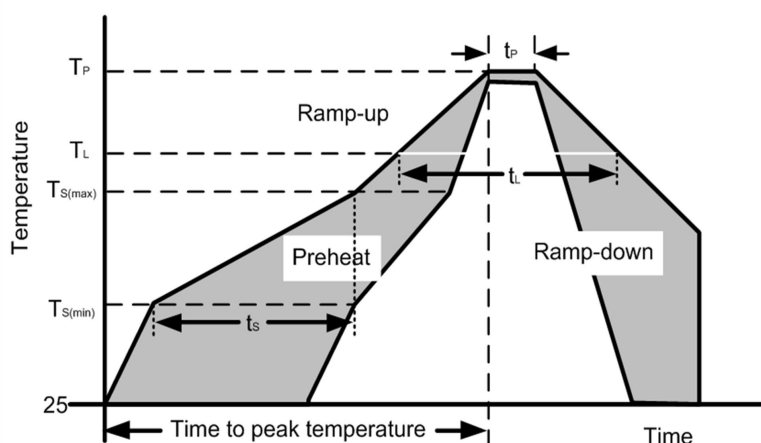


Figure 6: TLP Curve

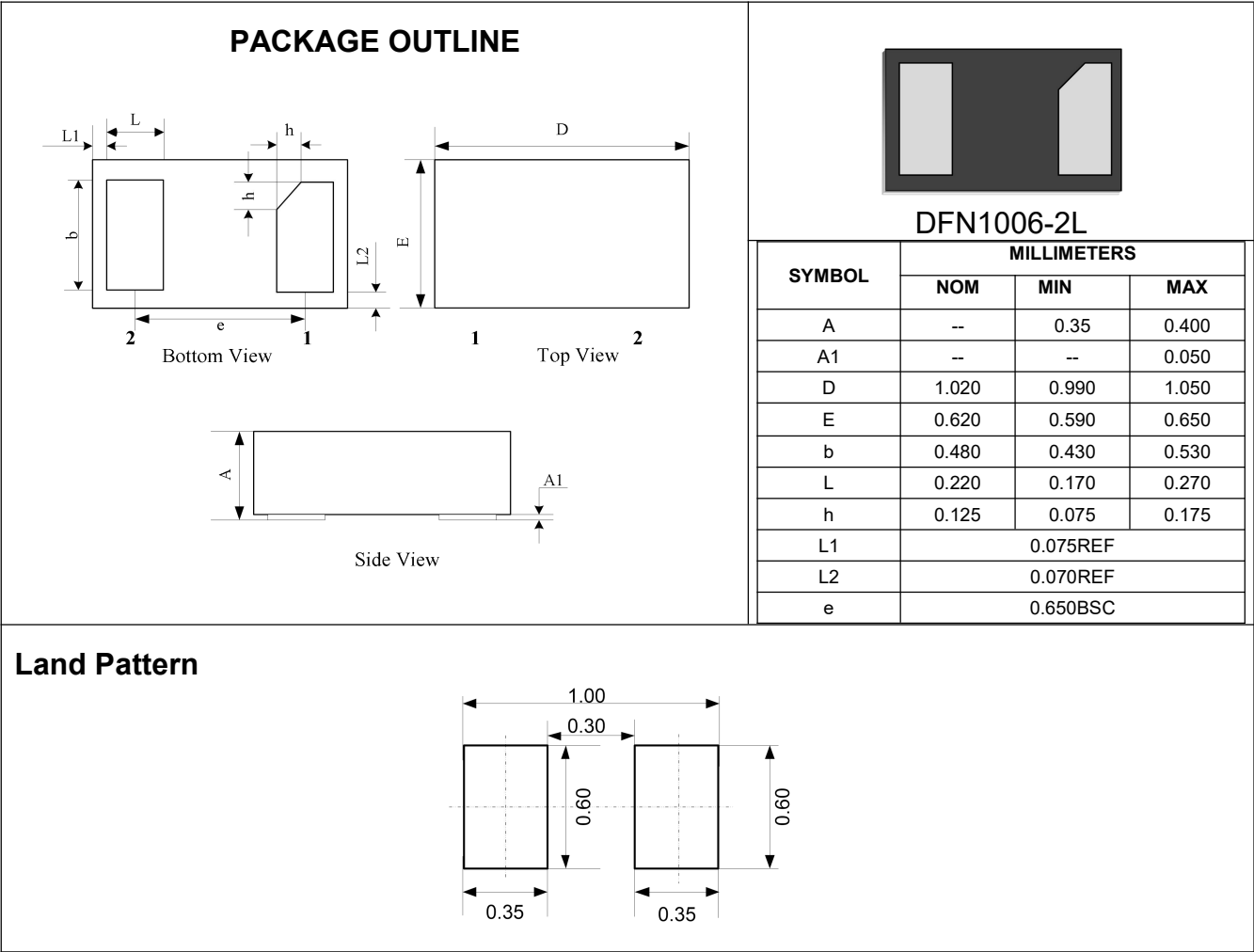


Soldering Parameters

Reflow Condition		Pb – Free assembly
Pre Heat	Temperature Min ($T_{s(min)}$)	150°C
	Temperature Max ($T_{s(max)}$)	200°C
	Time (min to max) (t_s)	60 – 190 secs
Average ramp up rate (Liquidus Temp) (T_L) to peak		5°C/second max
$T_{s(max)}$ to T_L ——Ramp-up Rate		5°C/second max
Reflow	Temperature (T_L) (Liquidus)	217°C
	Temperature (t_L)	60 – 150 seconds
Peak Temperature (T_P)		260+0/-5 °C
Time within actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		5°C/second max
Time 25°C to peak Temperature (T_P)		8 minutes Max.
Do not exceed		280°C



Outline Drawing –DFN1006-2L



Marking Codes

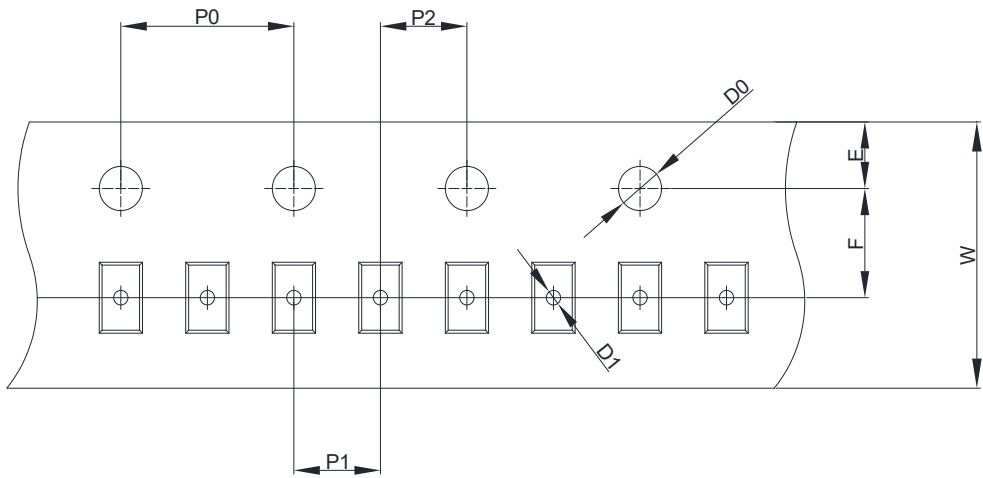
Part Number	Marking Code
ES15DFCX	1 QVX 2 QV=Specific Device Code X=Tracking Code

Package Information

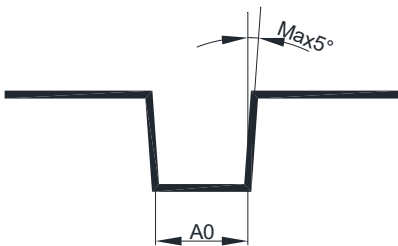
Qty: 10k/Reel

Tape Information

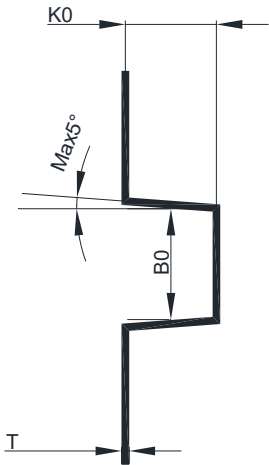
Tape Dimensions



top view

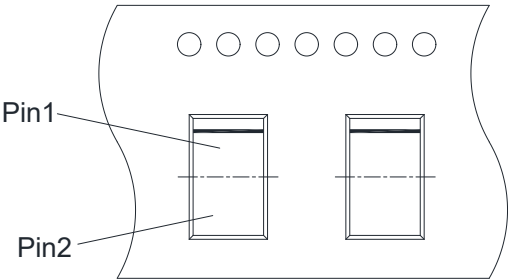


front view



end view

Quadrant Assignments For PIN1 Orientation In Tape



User Direction of Feed

SYMBOL	A0	B0	K0	P0	P1	P2
SPEC	0.69±0.05	1.19±0.05	0.53±0.05	4.00±0.10	2.00±0.10	2.00±0.05
SYMBOL	T	E	F	D0	D1	W
SPEC	0.20±0.03	1.75±0.10	3.50±0.05	1.55±0.05	0.50±0.10	8.00 ^{0.3} ±0.1

Revision History

No.	Version	Date	Revision Item	Request	Function and characteristic checking	Package dimension checking	Typos checking
1	1.0	2020-03-25	Released Version	Qi Shu Kun	Yin Peng	Ge Zheng Bing	Liu Jia Ying
2	1.1	2022-2-17	Update Tape Information	Qi Shu Kun	Yin Peng	Ge Zheng Bing	Liu Jia Ying